

Product Disassembly Instructions

Product Category:

Panel PC

Product Marketing Name / Model:

SPC-515

Purpose: The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.










| Item Description | Notes | BOM Detail | Quantity of items included in product |
|---|---|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board | 98935272400 (I3 M/B) 9893PW0802E (Power Board) 9693PH2302E (PH-23 USB HUB BOARD) 9680017378 (ELO Controller) | 4 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery | 1760000897-11 (BATTERY 3V/200 mAh W/CABLE BR2032 W/C) | 1 |
| External electrical cables and Power cord | | N/A | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 96LEDK-C150XG30NG1 | 1 |
| Cathode Ray Tubes (CRT) | | N/A | 0 |
| Gas Discharge Lamps | | N/A | 0 |

| | | | |
|--|--|-----|---|
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | N/A | 0 |
|--|--|-----|---|

| Item Description | Notes | Quantity of items included in product |
|--|---|--|
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Capacitors / condensers (Containing PCB) | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams | (Not including PCBs or PCAs already listed as a separate item above) | 0 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Asbestos waste and components which contain asbestos | | 0 |
| Components containing refractory ceramic fibers | | 0 |
| Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC) | | 0 |
| Components, parts and materials containing radioactive substances | | 0 |

2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

| Disassembly Tool | Picture |
|------------------|--|
| Screwdriver |  |
| Lever |  |
| Star Screwdriver |  |
| Hexagon Driver |  |
| Slanted pliers |  |
| Pliers |  |
| Hammer |  |
| Knife |  |
| Socket |  |
| Others | |

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

1. Disassembly 18 pcs screw to remove the rear cover.
2. Disassembly 6 pcs screw to remove the heatsink.
3. Disassembly 2 pcs screw to remove the SSD bracket from middle module bracket.
4. Disassembly 4 pcs screw to separate the SSD and SSD bracket.
5. Disassembly 1 pcs screw to remove the LED board.
6. Disassembly DDR module from DDR socket.
7. Disassembly 4 pcs screw to remove the controller board.
8. Disassembly 4 pcs screw to remove the M/B.
9. Disassembly 2 pcs screw to remove the USB HUB board.
10. Disassembly 4 pcs screw to remove the Power board.
11. Disassembly 6 pcs screw to remove the module bracket.
12. Disassembly screw 4pcs to remove the LCM.
13. Remove the waterproof from rear cover.

3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

